

SID

Factory: Rot am See

Article:

ML8

Provided:

Customer:

Date:

03.04.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	1	B00
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	139		2	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		3	
		35	L2		
C-RS-FR4-ML-0.508mm-035+035-TG150-HF-...	50203006	508		4	
		35	L3		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	124		5	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		6	
		35	L4		
C-RS-FR4-ML-0.508mm-035+035-TG150-HF-...	50203006	508		7	
		35	L5		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	124		8	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		9	
		35	L6		
C-RS-FR4-ML-0.508mm-035+035-TG150-HF-...	50203006	508		10	
		35	L7		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	139		11	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		12	
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	13	

Thickness after Pressing

B00:

2290 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2530 µm

Dmin:

2050 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2400 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2640 µm

Dmin:

2160 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

2330 µm

Version 1.2.20.35

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